

NUD3124, SZNUD3124

Automotive Inductive Load Driver

This micro-integrated part provides a single component solution to switch inductive loads such as relays, solenoids, and small DC motors without the need of a free-wheeling diode. It accepts logic level inputs, thus allowing it to be driven by a large variety of devices including logic gates, inverters, and microcontrollers.

Features

- Provides Robust Interface between D.C. Relay Coils and Sensitive Logic
- Capable of Driving Relay Coils Rated up to 150 mA at 12 Volts
- Replaces 3 or 4 Discrete Components for Lower Cost
- Internal Zener Eliminates Need for Free-Wheeling Diode
- Meets Load Dump and other Automotive Specs
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

Typical Applications

- Automotive and Industrial Environment
- Drives Window, Latch, Door, and Antenna Relays

Benefits

- Reduced PCB Space
- Standardized Driver for Wide Range of Relays
- Simplifies Circuit Design and PCB Layout
- Compliance with Automotive Specifications



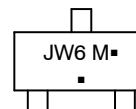
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MARKING DIAGRAMS



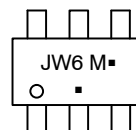
**SOT-23
CASE 318
STYLE 21**



JW6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)



**SC-74
CASE 318F
STYLE 7**



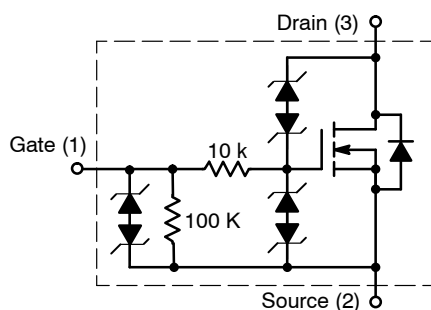
JW6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

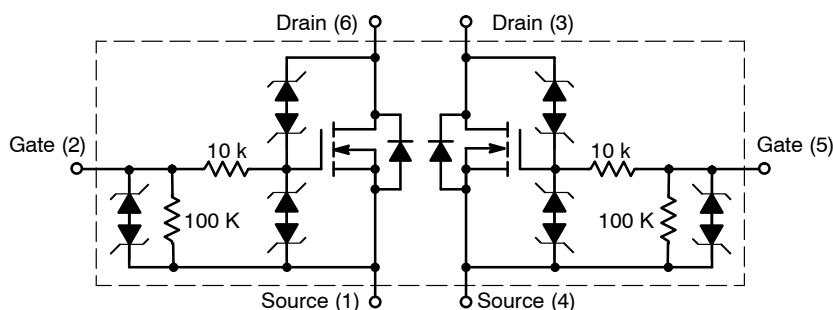
Device	Package	Shipping†
NUD3124LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SZNUD3124LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NUD3124DMT1G	SC-74 (Pb-Free)	3000 / Tape & Reel
SZNUD3124DMT1G	SC-74 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

INTERNAL CIRCUIT DIAGRAMS



CASE 318



CASE 318F

NUD3124, SZNUD3124

MAXIMUM RATINGS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Rating	Value	Unit
V_{DSS}	Drain-to-Source Voltage – Continuous ($T_J = 125^{\circ}\text{C}$)	28	V
V_{GSS}	Gate-to-Source Voltage – Continuous ($T_J = 125^{\circ}\text{C}$)	12	V
I_{D}	Drain Current – Continuous ($T_J = 125^{\circ}\text{C}$)	150	mA
E_{Z}	Single Pulse Drain-to-Source Avalanche Energy (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T_J Initial = 85°C)	250	mJ
P_{PK}	Peak Power Dissipation, Drain-to-Source (Notes 1 and 2) (T_J Initial = 85°C)	20	W
E_{LD1}	Load Dump Suppressed Pulse, Drain-to-Source (Notes 3 and 4) (Suppressed Waveform: $V_s = 45\text{ V}$, $R_{\text{SOURCE}} = 0.5\ \Omega$, $T = 200\text{ ms}$) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T_J Initial = 85°C)	80	V
E_{LD2}	Inductive Switching Transient 1, Drain-to-Source (Waveform: $R_{\text{SOURCE}} = 10\ \Omega$, $T = 2.0\text{ ms}$) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T_J Initial = 85°C)	100	V
E_{LD3}	Inductive Switching Transient 2, Drain-to-Source (Waveform: $R_{\text{SOURCE}} = 4.0\ \Omega$, $T = 50\ \mu\text{s}$) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T_J Initial = 85°C)	300	V
Rev-Bat	Reverse Battery, 10 Minutes (Drain-to-Source) (For Relay's Coils/Inductive Loads of 80 Ω or more)	-14	V
Dual-Volt	Dual Voltage Jump Start, 10 Minutes (Drain-to-Source)	28	V
ESD	Human Body Model (HBM) According to EIA/JESD22/A114 Specification	2,000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Nonrepetitive current square pulse 1.0 ms duration.
2. For different square pulse durations, see Figure 2.
3. Nonrepetitive load dump suppressed pulse per Figure 3.
4. For relay's coils/inductive loads higher than 80 Ω , see Figure 4.

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THERMAL CHARACTERISTICS

Symbol	Rating	Value	Unit
T _A	Operating Ambient Temperature	–40 to 125	°C
T _J	Maximum Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	–65 to 150	°C
P _D	Total Power Dissipation (Note 5) Derating above 25°C	SOT–23 225 1.8	mW
			mW/°C
P _D	Total Power Dissipation (Note 5) Derating above 25°C	SC–74 380 3.0	mW
			mW/°C
R _{θJA}	Thermal Resistance Junction–to–Ambient (Note 5)	SOT–23 556	°C/W
		SC–74 329	

5. Mounted onto minimum pad board.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain to Source Sustaining Voltage ($I_D = 10\text{ mA}$)	V_{BRDSS}	28	34	38	V
Drain to Source Leakage Current ($V_{DS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$) ($V_{DS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$) ($V_{DS} = 28\text{ V}$, $V_{GS} = 0\text{ V}$) ($V_{DS} = 28\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$)	I_{DSS}	– – – –	– – – –	0.5 1.0 50 80	μA
Gate Body Leakage Current ($V_{GS} = 3.0\text{ V}$, $V_{DS} = 0\text{ V}$) ($V_{GS} = 3.0\text{ V}$, $V_{DS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$) ($V_{GS} = 5.0\text{ V}$, $V_{DS} = 0\text{ V}$) ($V_{GS} = 5.0\text{ V}$, $V_{DS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$)	I_{GSS}	– – – –	– – – –	60 80 90 110	μA

ON CHARACTERISTICS

Gate Threshold Voltage ($V_{GS} = V_{DS}$, $I_D = 1.0\text{ mA}$) ($V_{GS} = V_{DS}$, $I_D = 1.0\text{ mA}$, $T_J = 125^\circ\text{C}$)	$V_{GS(th)}$	1.3 1.3	1.8 –	2.0 2.0	V
Drain to Source On-Resistance ($I_D = 150\text{ mA}$, $V_{GS} = 3.0\text{ V}$) ($I_D = 150\text{ mA}$, $V_{GS} = 3.0\text{ V}$, $T_J = 125^\circ\text{C}$) ($I_D = 150\text{ mA}$, $V_{GS} = 5.0\text{ V}$) ($I_D = 150\text{ mA}$, $V_{GS} = 5.0\text{ V}$, $T_J = 125^\circ\text{C}$)	$R_{DS(on)}$	– – – –	– – – –	1.4 1.7 0.8 1.1	Ω
Output Continuous Current ($V_{DS} = 0.25\text{ V}$, $V_{GS} = 3.0\text{ V}$) ($V_{DS} = 0.25\text{ V}$, $V_{GS} = 3.0\text{ V}$, $T_J = 125^\circ\text{C}$)	$I_{DS(on)}$	150 140	200 –	– –	mA
Forward Transconductance ($V_{DS} = 12\text{ V}$, $I_D = 150\text{ mA}$)	g_{FS}	–	500	–	mmho

DYNAMIC CHARACTERISTICS

Input Capacitance ($V_{DS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	C_{iss}	–	32	–	pf
Output Capacitance ($V_{DS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	C_{oss}	–	21	–	pf
Transfer Capacitance ($V_{DS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	C_{rss}	–	8.0	–	pf

SWITCHING CHARACTERISTICS

Propagation Delay Times: High to Low Propagation Delay; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 3.0\text{ V}$) Low to High Propagation Delay; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 3.0\text{ V}$) High to Low Propagation Delay; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 5.0\text{ V}$) Low to High Propagation Delay; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 5.0\text{ V}$)	t_{PHL} t_{PLH} t_{PHL} t_{PLH}	– – – –	890 912 324 1280	– – – –	ns
Transition Times: Fall Time; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 3.0\text{ V}$) Rise Time; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 3.0\text{ V}$) Fall Time; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 5.0\text{ V}$) Rise Time; Figure 1, ($V_{DS} = 12\text{ V}$, $V_{GS} = 5.0\text{ V}$)	t_f t_r t_f t_r	– – – –	2086 708 556 725	– – – –	ns

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TYPICAL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)

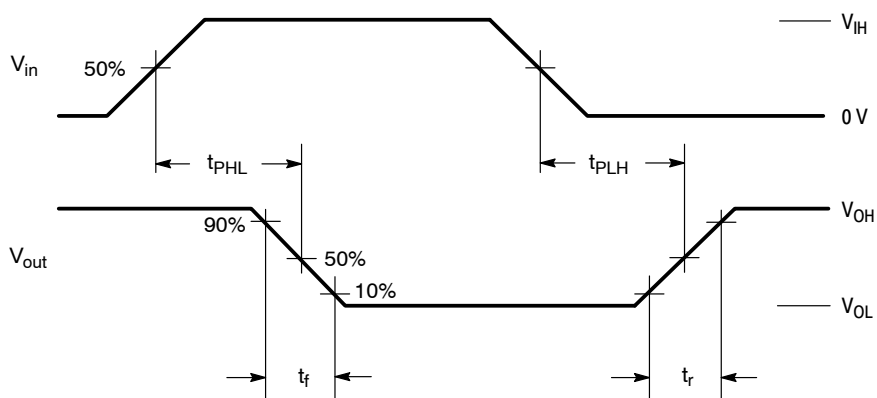


Figure 1. Switching Waveforms

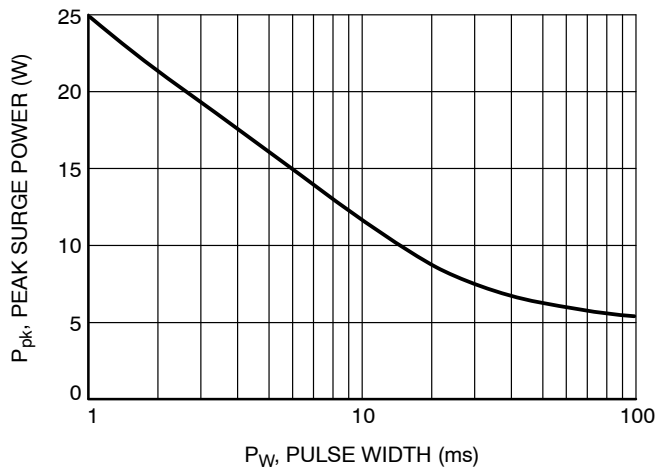


Figure 2. Maximum Non-repetitive Surge Power versus Pulse Width

Load Dump Pulse Not Suppressed:

$V_R = 13.5\text{ V Nominal } \pm 10\%$

$V_S = 60\text{ V Nominal } \pm 10\%$

$T = 300\text{ ms Nominal } \pm 10\%$

$T_R = 1 - 10\text{ ms } \pm 10\%$

Load Dump Pulse Suppressed:

NOTE: Max. Voltage DUT is exposed to is approximately 45 V.

$V_S = 30\text{ V } \pm 20\%$

$T = 150\text{ ms } \pm 20\%$

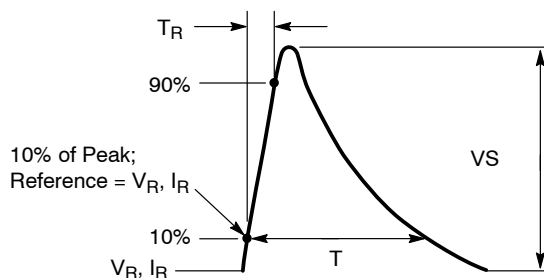


Figure 3. Load Dump Waveform Definition

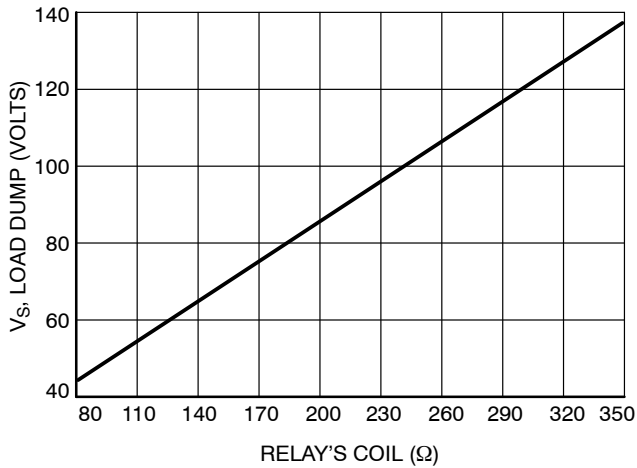


Figure 4. Load Dump Capability versus Relay's Coil dc Resistance

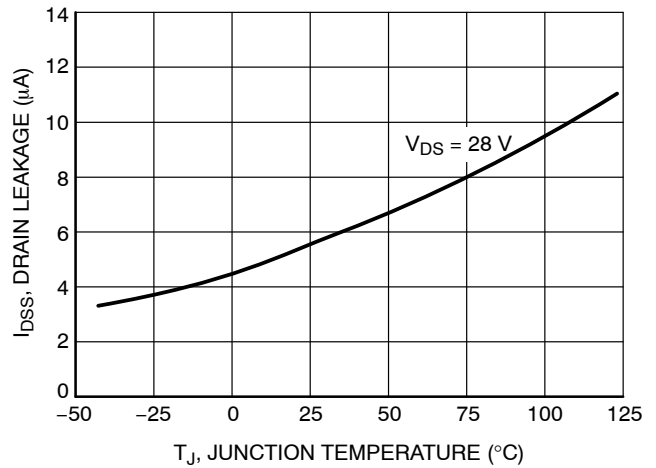


Figure 5. Drain-to-Source Leakage versus Junction Temperature

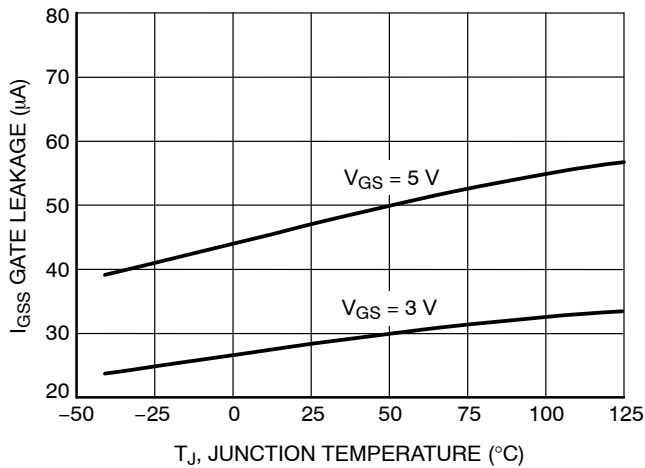


Figure 6. Gate-to-Source Leakage versus Junction Temperature

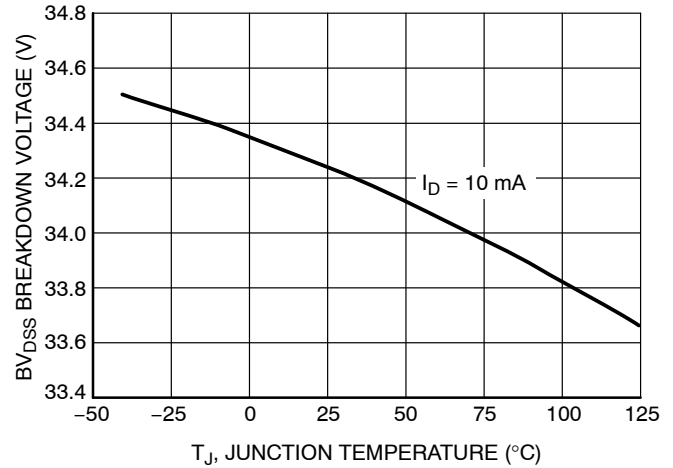


Figure 7. Breakdown Voltage versus Junction Temperature

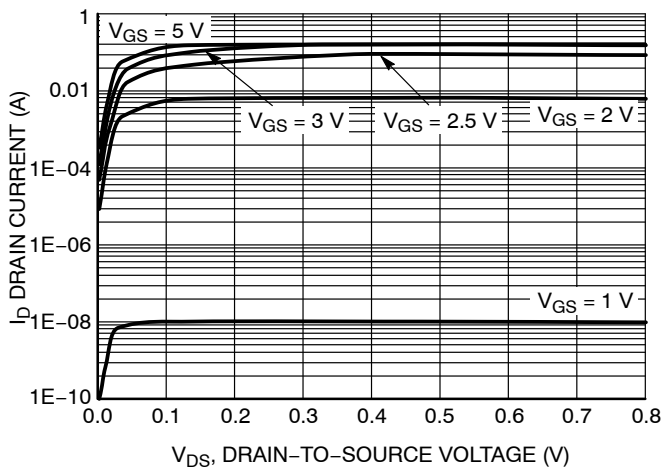


Figure 8. Output Characteristics

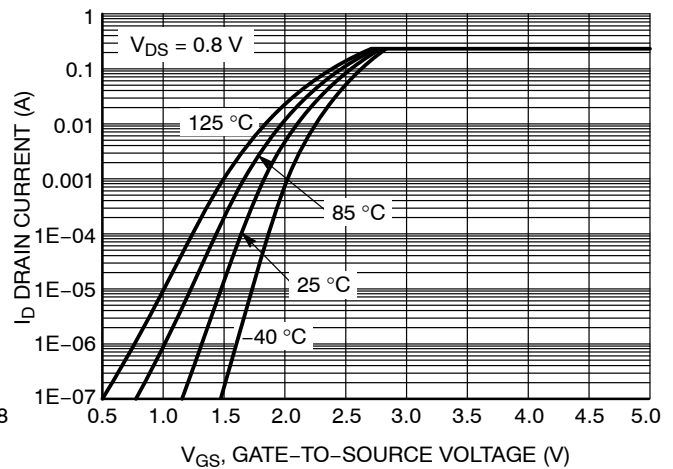


Figure 9. Transfer Function

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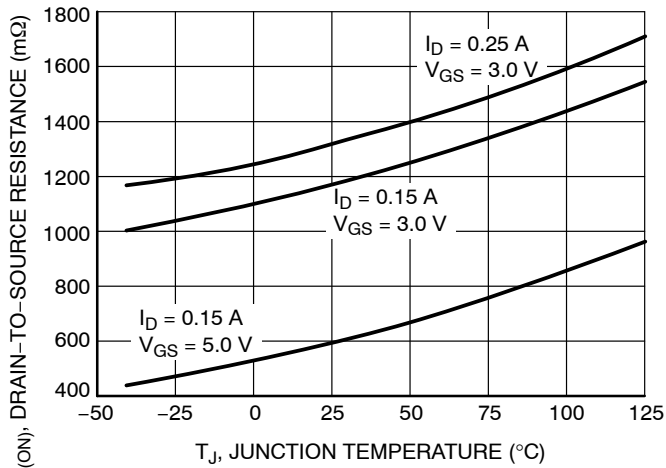


Figure 10. On Resistance Variation versus Junction Temperature

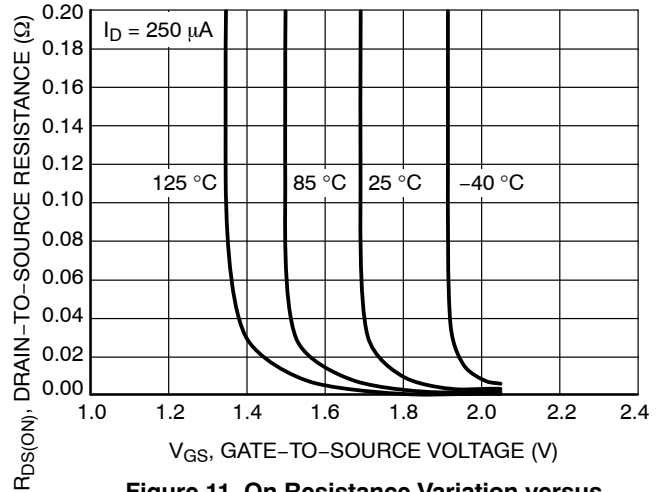


Figure 11. On Resistance Variation versus Gate-to-Source Voltage

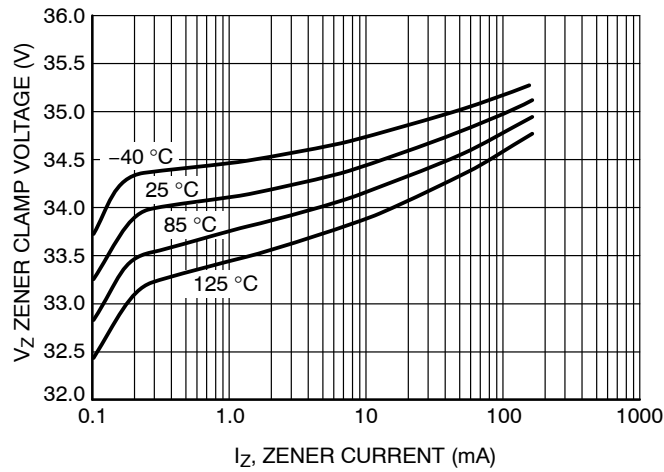


Figure 12. Zener Clamp Voltage versus Zener Current

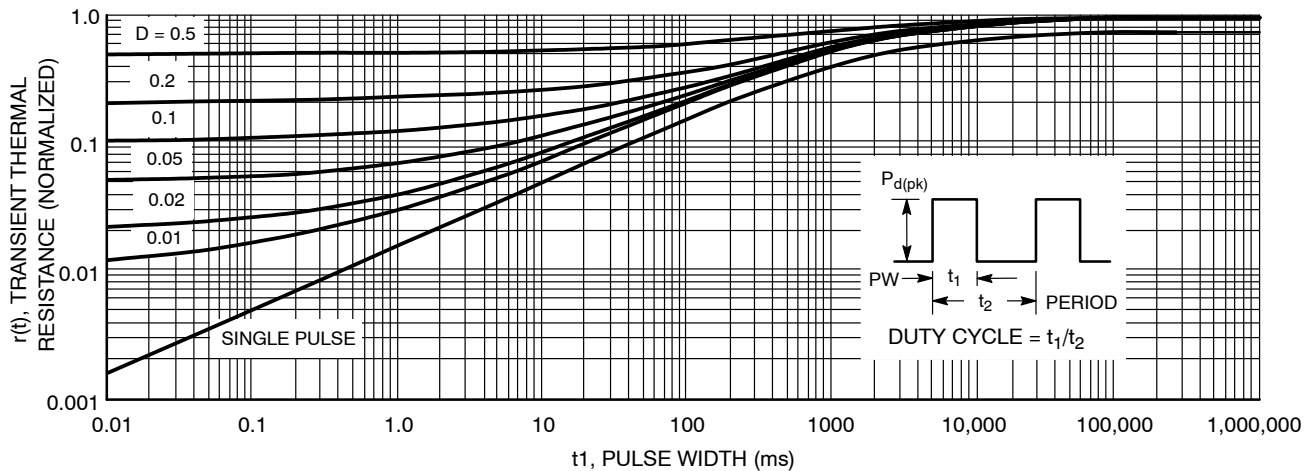


Figure 13. Transient Thermal Response for NUD3124LT1G

NUD3124, SZNUD3124

APPLICATIONS INFORMATION

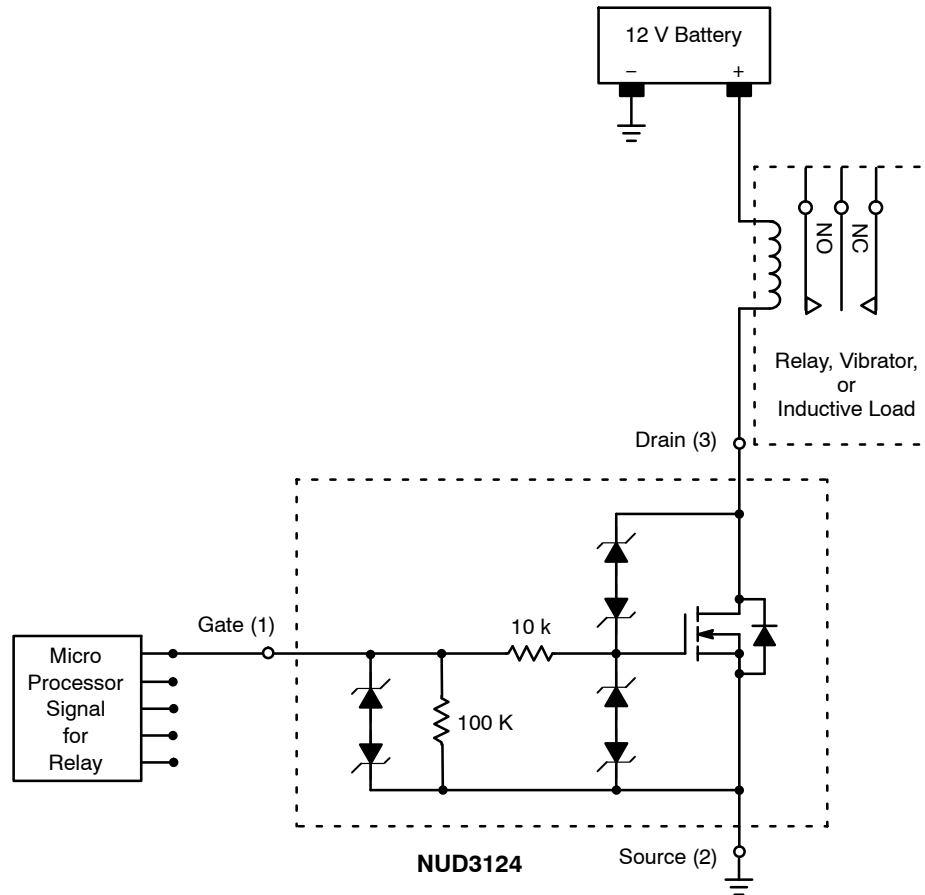
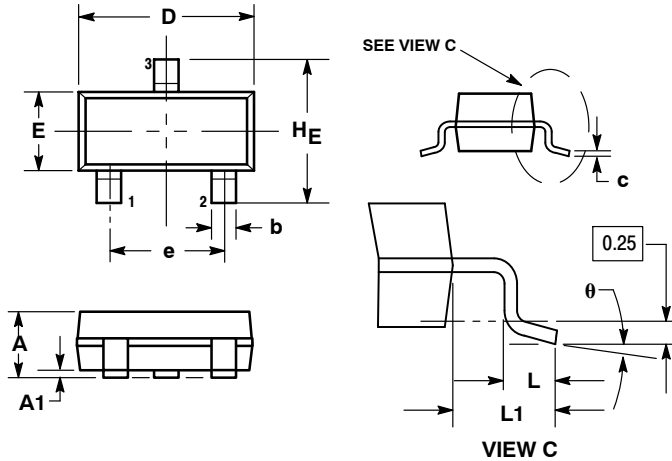


Figure 14. Applications Diagram

NUD3124, SZNUD3124

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AP

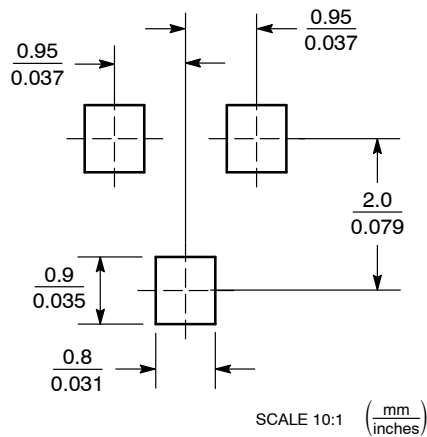


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

SOLDERING FOOTPRINT*

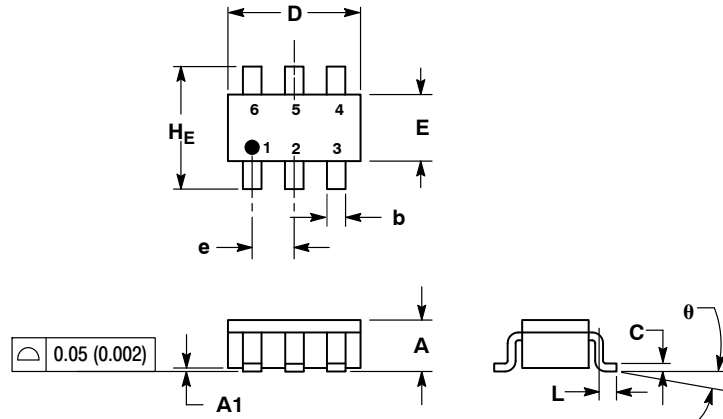


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NUD3124, SZNUD3124

PACKAGE DIMENSIONS

SC-74 CASE 318F-05 ISSUE M



NOTES:

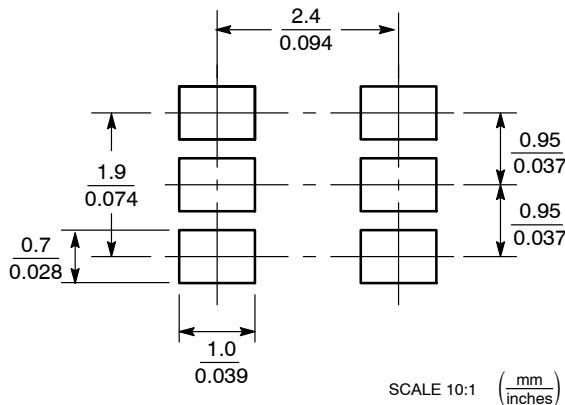
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
theta	0°	—	10°	0°	—	10°

STYLE 7:

- PIN 1. SOURCE 1
- GATE 1
- DRAIN 2
- SOURCE 2
- GATE 2
- DRAIN 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

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